



Specification of Automotive MLCC

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N :
- CL21B683KBC5PNC
- Description : CAP, 68nF, 50V, ±10%, X7R, 0805
- AEC-Q 200 Specified

A. Samsung Part Number

| | | <u>C</u> | <u>L 2</u> | <u>1 E</u> | <u>683</u> | <u>K</u> | <u>B</u> | <u>C</u> | <u>5</u> | <u>P</u> | N | <u>C</u> |
|------------|---------------|---------------------------------------|------------|------------|------------|----------|----------|----------|----------|----------|----|-------------------------|
| | | 0 | |) (3 |) (4) | 5 | 6 | 1 | (8) | 9 | 10 | 1 |
| 1 | Series | Samsung Multi-layer Ceramic Capacitor | | | | | | | | | | |
| 2 | Size | 0805 (inc | | | | |) ± 0.1 | mm | | | W: | 1.25 ± 0.1 mm |
| (3) | Dielectric | X7R | | | | (8) | Inne | r elec | trode | | | Ni , Open mode |
| 4 | Capacitance | 68 nF | | | | Ŭ | Tern | ninati | on | | | Cu , Ag-epoxy |
| 5 | Capacitance | ±10 % | | | | | Plati | ng | | | | Sn 100% (Pb Free) |
| | tolerance | | | | | 9 | Prod | luct | | | | Automotive |
| 6 | Rated Voltage | 50 V | | | | 10 | Grac | le coo | le | | | Standard |
| \bigcirc | Thickness | 0.85 ± 0. | 1 m | n | | 1 | Pack | aging | 9 | | | Cardboard Type, 7" reel |

B. Reliablility Test and Judgement condition

| | Performance | Test condition | | | | |
|----------------------|---|---|--|--|--|--|
| High Temperature | Appearance : No abnormal exterior appearance | Unpowered, 1000hrs@T=150℃ | | | | |
| Exposure | Capacitance Change : Within ±10% | Measurement at 24±2hrs after test conclusion | | | | |
| | Tan δ: 0.03 max | | | | | |
| | IR : More than 10,000 Ω or 500 $\Omega \times \mu F$ | | | | | |
| | Whichever is Smaller | | | | | |
| Temperature Cycling | Appearance : No abnormal exterior appearance | 1000Cycles | | | | |
| | Capacitance Change : Within ±10% | Measurement at 24±2hrs after test conclusion | | | | |
| | Tan δ: 0.03 max | 1 cycle condition : | | | | |
| | IR : More than 10,000 Ω or 500 $\Omega \times \mu F$ | -55+0/-3℃(15±3min) -> Room Temp(1min.) | | | | |
| | Whichever is Smaller | -> 125+3/-0℃(15±3min) -> Room Temp(1min.) | | | | |
| Destructive Physical | No Defects or abnormalities | Per EIA 469 | | | | |
| Analysis | | | | | | |
| Moisture Resistance | Appearance : No abnormal exterior appearance | 10Cycles, t=24hrs/cycle | | | | |
| | Capacitance Change : Within ±12.5% | Heat (25~65 $^\circ C$) and humidity (80~98%), Unpowered | | | | |
| | Tan δ: 0.03 max | measurement at 24±2hrs after test conclusion | | | | |
| | IR : More than 10,000 $\mbox{M}\Omega$ or 500 $\mbox{M}\Omega \times \mu F$ | | | | | |
| | Whichever is Smaller | | | | | |
| Humidity Bias | Appearance : No abnormal exterior appearance | 1000hrs 85℃/85%RH, Rated Voltate and 1.3~1.5V, | | | | |
| | Capacitance Change : Within ±12.5% | Add 100kohm resistor | | | | |
| | Tan δ: 0.035 max | Measurement at 24±2hrs after test conclusion | | | | |
| | IR : More than 500MΩ or 25 MΩ× μ F | The charge/discharge current is less than 50mA. | | | | |
| | Whichever is Smaller | | | | | |
| High Temperature | Appearance : No abnormal exterior appearance | 1000hrs @ TA=125℃, 200% Rated Voltage, | | | | |
| Operating Life | Capacitance Change : Within ±12.5% | Measurement at 24±2hrs after test conclusion | | | | |
| | Tan δ: 0.035 max | The charge/discharge current is less than 50mA. | | | | |
| | IR : More than 1000№ or 50№×µF | | | | | |
| | Whichever is Smaller | | | | | |

| | Performance | Test condition | | | | | |
|---------------------|---|---|--|--|--|--|--|
| External Visual | No abnormal exterior appearance | Microscope (`10) | | | | | |
| | | | | | | | |
| Physical Dimensions | Within the specified dimensions | Using The calipers | | | | | |
| Mechanical Shock | Appearance : No abnormal exterior appearance | Three shocks in each direction should be applied along | | | | | |
| Mechanical Shock | Capacitance Change : Within ±10% | 3 mutually perpendicular axes of the test specimen (18 shocks) | | | | | |
| | Tan δ , IR : initial spec. | Peakvalue Duration Wave Velocity | | | | | |
| | | 1,500G 0.5ms Half sine 4.7m/sec. | | | | | |
| | | | | | | | |
| Vibration | Appearance : No abnormal exterior appearance | 5g's for 20min., 12cycles each of 3 orientations, | | | | | |
| | Capacitance Change : Within ±10% | Use 8"×5" PCB 0.031" Thick 7 secure points on one long side | | | | | |
| | Tan δ, IR : initial spec. | and 2 secure points at corners of opposite sides. Parts mounted | | | | | |
| | | within 2" from any secure point. Test from $10~2000$ Hz. | | | | | |
| Resistance to | Appearance : No abnormal exterior appearance | Solder pot : 260±5℃, 10±1sec. | | | | | |
| Solder Heat | Capacitance Change : Within ±10% | | | | | | |
| | Tan δ, IR : initial spec. | | | | | | |
| Thermal Shock | Appearance : No abnormal exterior appearance | -55℃/+125℃. | | | | | |
| Thermal onock | Capacitance Change : Within ±10% | Note: Number of cycles required-300, | | | | | |
| | Tan δ , IR : initial spec. | Maximum transfer time-20 sec, Dwell time-15min. Air-Air | | | | | |
| | | | | | | | |
| ESD | Appearance : No abnormal exterior appearance | AEC-Q200-002 | | | | | |
| | Capacitance Change : Within ±10% | | | | | | |
| | Tan δ, IR : initial spec. | | | | | | |
| Solderability | 95% of the terminations is to be soldered | a) Preheat at 155℃ for 4 hours, Immerse in solder for 5s at 245±5℃ | | | | | |
| | evenly and continuously | b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5℃ | | | | | |
| | | c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5℃ | | | | | |
| | | solder : a solution ethanol and rosin | | | | | |
| Electrical | Capacitance : Within specified tolerance | The Capacitance /D.F. should be measured at 25 $^\circ\!\!\mathbb{C}$, | | | | | |
| Characterization | Tan δ (DF)0.025 max. | 1ktz±10%, 1.0±0.2Vrms | | | | | |
| | IR(25℃) : More than 10,000№ or 500№× <i>μ</i> F | I.R. should be measured with a DC voltage not exceeding | | | | | |
| | IR(125 °C) : More than1,000№ or 10№× μ F | Rated Voltage @25°C, @125°C for 60~120 sec. | | | | | |
| | Whichever is Smaller | | | | | | |
| | Dielectric Strength | Dielectric Strength : 250% of the rated voltage for 1~5 seconds | | | | | |
| Board Flex | Appearance : No abnormal exterior appearance | Bending to the limit (2mm) for 5 seconds | | | | | |
| | Capacitance Change : Within ±10% | | | | | | |
| Terminal | Appearance : No abnormal exterior appearance | 18N, for 60±1 sec. | | | | | |
| Strength(SMD) | Capacitance Change : Within ±10% | | | | | | |
| | | | | | | | |
| Beam Load | Destruction value should not be exceed | Beam speed | | | | | |
| | Chip Length < 2.5mm | 0.5±0.05mm/sec | | | | | |
| | a) Chip Thickness > 0.5㎜ : 20N | | | | | | |
| | b) Chip Thickness \leq 0.5mm : 8N | | | | | | |
| Temperature | X7R | | | | | | |
| Characterisitcs | (From -55℃ to 125℃, Capacitance change sho | ud be within ±15%) | | | | | |

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^\circ$, 10sec. Max) Meet IPC/JEDEC J-STD-020 D Standard

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.